

AMENDMENT TO THE CLAIMS

1-10. (cancelled)

11. (Previously Presented): A wafer comprising a glide head array including a plurality of rows and a plurality of columns of glide portions having air bearing surfaces formed on a surface of the wafer and an array of glide transducers on the wafer to form a plurality of glide heads.

12. (Currently Amended): The wafer of claim 11 wherein the array of ~~air bearing surfaces~~ comprise rails.

13. (Previously Presented): The wafer of claim 11 wherein said surface of the wafer has a flatness less than about 3  $\mu\text{m}$ .

14. (Previously Presented): The wafer of claim 11 wherein the wafer comprises aluminum oxide/titanium carbide.

15. (Previously Presented): The wafer of claim 11 wherein the surface of the wafer has a peak-to-valley flatness less than about 1  $\mu\text{inch}$ .

16. (Previously Presented): The wafer of claim 11 wherein the surface of the wafer has a surface flatness less than about 1  $\mu\text{inch}$ .

17. (Previously Presented): A wafer comprising a glide head array including a plurality of rows and a plurality of columns of glide portions having air bearing surfaces formed on a surface of the wafer and an array of glide transducers on the wafer to form a plurality of glide heads wherein the array of glide transducers are mounted on a wafer surface opposite to the surface of the wafer having the air bearing surfaces formed thereon.

18. (Previously Presented): The wafer of claim 11 wherein the surface of the wafer has a flatness less than about 0.5  $\mu$ inch.

19. (Previously Presented): A glide head formed from a wafer comprising a plurality of rows and a plurality of columns of glide portions having a plurality of air bearing surfaces formed on a surface of the wafer and an array of glide transducers on the wafer and the glide head formed from one of said glide portions.

20. (Previously Presented): A detection system for detecting asperities comprising the glide head of claim 19 supported on an armature operable to position the glide head over a disc surface for glide testing and including a transducer on the glide head to detect interactions between the glide head and the disc surface.

21. (Previously Presented): The wafer of claim 11 where the array of glide transducers includes an array of piezoelectric transducers.

22. (Previously Presented): The wafer of claim 17 wherein the glide head array includes an array of wing portions and the array of glide transducers are formed thereon.

23. (Previously Presented): The wafer of claim 11 wherein the array of glide transducers are formed on the surface of the wafer having the air bearing surfaces formed thereon.

24. (Currently Amended): A wafer comprising a glide head array including a plurality of rows and a plurality of columns of glide portions having air bearing surfaces formed on a surface of the wafer and an array of glide transducers on the wafer to form a plurality of glide heads wherein the array of glide transducers includes an array of thermal transducers formed on a the surface of the wafer having the air bearing surfaces formed thereon.

25. (Previously Presented): The wafer of claim 24 wherein the thermal transducers of the array of thermal transducers are formed of magnetoresistive sensors.

26. (Previously Presented): The wafer of claim 11 wherein the air bearing surfaces of the plurality of rows and the plurality of columns of glide portions are formed using one of or a combination of saw cutting, milling or deposition techniques.

27. (Previously Presented): The wafer of claim 11 wherein the glide head array includes an array of wing portions and the array of glide transducers are formed thereon.